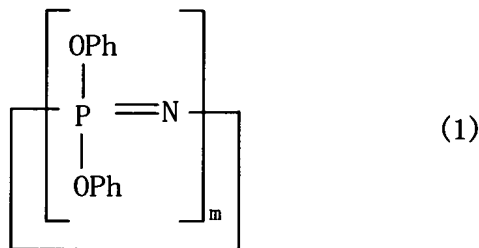


CLAIM AMENDMENTS

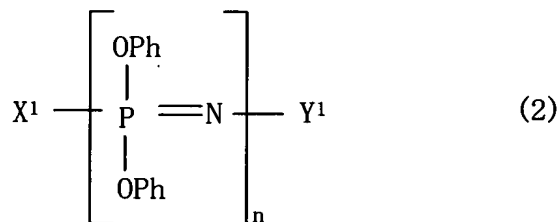
1.-3. (canceled)

4. (currently amended) ~~The heat-resistant component according to claim 1, A~~
heat-resistant composition containing solvent-soluble polyimide resin (A), a phosphazene
compound (B), and a reactive compound (C) selected from at least one of an epoxy
compound, an acrylic compound, and an isocyanate compound, wherein
the phosphazene compound (B) includes at least either a cyclic phenoxyphosphazene
compound (B1) expressed in the following chemical formula (1):



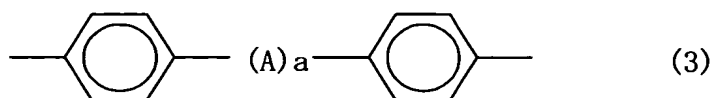
where m represents an integer of 3 to 25, and Ph represents a phenyl group,

or a chain phenoxyphosphazene compound (B2) expressed in the following chemical
formula (2):



where X¹ represents group-N = P(OPh)₃ or group-N = P(O)OPh, Y¹ represents
group-P(OPh)₄, or group-P(O)(OPh)₂, n represents an integer of 3 to 10,000, and Ph
represents a phenyl group,

or a cross-linked phenoxyphosphazene compound (B3) cross-linked by a cross-
linking group including at least one of an o-phenylene group, an m-phenylene group, a p-
phenylene group, and a bisphenylene group expressed in the following chemical formula (3):



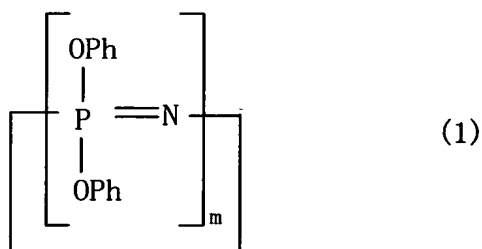
where A represents $-\text{C}(\text{CH}_3)_2-$, $-\text{SO}_2-$, $-\text{S}-$, or $-\text{O}-$, and a represents 0 or 1, with respect to the phosphazene compound including at least either the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B),

so that the cross-linking group intervenes between two oxygen atoms desorbed by the phenyl group of the phosphazene compound, and the phenyl group content is 50 to 99.9 % with reference to the total number of phenyl groups contained in the phosphazene compound including at least the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B2) with no free hydroxyl groups in molecules, and

wherein said the polyimide resin (A) is a polyamide imide resin, and said the reactive compound (C) is an epoxy compound.

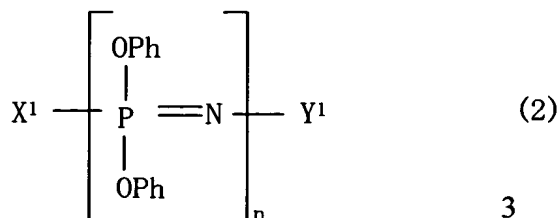
5. (currently amended) ~~The heat-resistant component according to claim 1, A~~ heat-resistant composition containing solvent-soluble polyimide resin (A), a phosphazene compound (B), and a reactive compound (C) selected from at least one of an epoxy compound, an acrylic compound, and an isocyanate compound, wherein

the phosphazene compound (B) includes at least either a cyclic phenoxyphosphazene compound (B1) expressed in the following chemical formula (1):



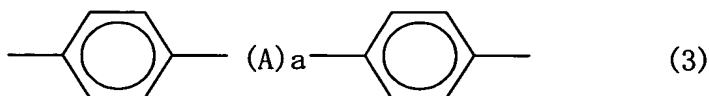
where m represents an integer of 3 to 25, and Ph represents a phenyl group,

or a chain phenoxyphosphazene compound (B2) expressed in the following chemical formula (2):



where X^1 represents group $-N = P(OPh)_3$ or group $-N = P(O)OPh$, Y^1 represents group $-P(OPh)_4$, or group $-P(O)(OPh)_2$, n represents an integer of 3 to 10,000, and Ph represents a phenyl group,

or a cross-linked phenoxyphosphazene compound (B3) cross-linked by a cross-linking group including at least one of an o-phenylene group, an m-phenylene group, a p-phenylene group, and a bisphenylene group expressed in the following chemical formula (3):

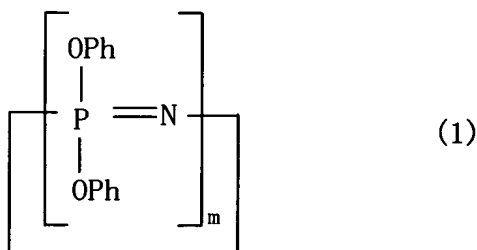


where A represents $-C(CH_3)_2-$, $-SO_2-$, $-S-$, or $-O-$, and a represents 0 or 1, with respect to the phosphazene compound including at least either the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B),

so that the cross-linking group intervenes between two oxygen atoms desorbed by the phenyl group of the phosphazene compound, and the phenyl group content is 50 to 99.9 % with reference to the total number of phenyl groups contained in the phosphazene compound including at least the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B2) with no free hydroxyl groups in molecules, and

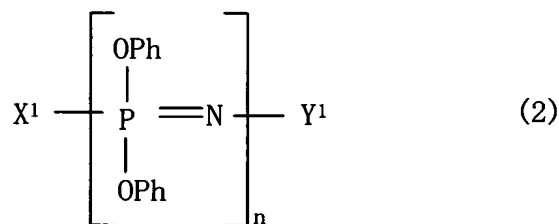
wherein said the polyimide resin (A) is polyester imide resin, and said the reactive compound (C) is an epoxy compound.

6. (currently amended) ~~The heat-resistant component according to claim 1, A~~ heat-resistant composition containing solvent-soluble polyimide resin (A), a phosphazene compound (B), and a reactive compound (C) selected from at least one of an epoxy compound, an acrylic compound, and an isocyanate compound, wherein the phosphazene compound (B) includes at least either a cyclic phenoxyphosphazene compound (B1) expressed in the following chemical formula (1):



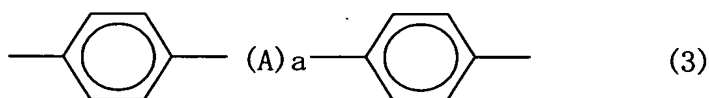
where m represents an integer of 3 to 25, and Ph represents a phenyl group,

or a chain phenoxyphosphazene compound (B2) expressed in the following chemical formula (2):



where X^1 represents group- $\text{N} = \text{P}(\text{OPh})_3$ or group- $\text{N} = \text{P}(\text{O})\text{OPh}$, Y^1 represents group- $\text{P}(\text{OPh})_4$, or group- $\text{P}(\text{O})(\text{OPh})_2$, n represents an integer of 3 to 10,000, and Ph represents a phenyl group,

or a cross-linked phenoxyphosphazene compound (B3) cross-linked by a cross-linking group including at least one of an o-phenylene group, an m-phenylene group, a p-phenylene group, and a bisphenylene group expressed in the following chemical formula (3):



where A represents $-\text{C}(\text{CH}_3)_2-$, $-\text{SO}_2-$, $-\text{S}-$, or $-\text{O}-$, and a represents 0 or 1, with respect to the phosphazene compound including at least either the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B),

so that the cross-linking group intervenes between two oxygen atoms desorbed by the phenyl group of the phosphazene compound, and the phenyl group content is 50 to 99.9 % with reference to the total number of phenyl groups contained in the phosphazene compound including at least the cyclic phenoxyphosphazene compound (B1) or the chain phenoxyphosphazene compound (B2) with no free hydroxyl groups in molecules, and wherein said the polyimide resin (A) is polyether imide resin, and said the reactive compound (C) is an epoxy compound.

7. (currently amended) An adhesive for a printed wiring board employing the heat-resistant composition according to claim 4.

8. (currently amended) An adhesive sheet for a printed wiring board employing the heat-resistant composition according to claim 1 4.

9. (currently amended) A multilayer printed wiring board employing the heat-resistant composition according to claim 1 4.

10. (currently amended) A sealant for a printed wiring board employing the heat-resistant composition according to claim 1 4.

11. (currently amended) An insulating circuit protective film for a printed wiring board employing the heat-resistant composition according to claim 1 4.

12. (currently amended) A circuit protective agent employing the heat-resistant composition according to claim 1 4.

13. (currently amended) A cover-lay film employing the heat-resistant composition according to claim 1 4.

14. (currently amended) A cover ink employing the heat-resistant composition according to claim 1 4.

15. (currently amended) A substrate for a printed wiring board employing the heat-resistant composition according to claim 1 4.

16. (currently amended) A metal-clad laminate employing the heat-resistant composition according to claim 1 4.

17. (currently amended) A conductive paste for a printed wiring board employing the heat-resistant composition according to claim 1 4.

18. (new) The heat-resistant composition according to claim 4, wherein the polyimide resin (A) comprises a solvent solubility imparting component selected from at least one of an aliphatic compound component, an alicyclic compound component, and an alkylene

oxide adduct component of a bisphenol compound, soluble in a solvent containing a low-boiling solvent.

19. (new) The heat-resistant composition according to claim 5, wherein the polyimide resin (A) comprises a solvent solubility imparting component selected from at least one of an aliphatic compound component, an alicyclic compound component, and an alkylene oxide adduct component of a bisphenol compound, soluble in a solvent containing a low-boiling solvent.

20. (new) An adhesive for a printed wiring board employing the heat-resistant composition according to claim 5.

21. (new) An adhesive sheet for a printed wiring board employing the heat-resistant composition according to claim 5.

22. (new) A multilayer printed wiring board employing the heat-resistant composition according to claim 5.

23. (new) A sealant for a printed wiring board employing the heat-resistant composition according to claim 5.

24. (new) An insulating circuit protective film for a printed wiring board employing the heat-resistant composition according to claim 5.

25. (new) A circuit protective agent employing the heat-resistant composition according to claim 5.

26. (new) A cover-lay film employing the heat-resistant composition according to claim 5.

27. (new) A cover ink employing the heat-resistant composition according to claim 5.

28. (new) A substrate for a printed wiring board employing the heat-resistant composition according to claim 5.

29. (new) A metal-clad laminate employing the heat-resistant composition according to claim 5.

30. (new) A conductive paste for a printed wiring board employing the heat-resistant composition according to claim 5.

31. (new) The heat-resistant composition according to claim 6, wherein the polyimide resin (A) comprises a solvent solubility imparting component selected from at least one of an aliphatic compound component, an alicyclic compound component, and an alkylene oxide adduct component of a bisphenol compound, soluble in a solvent containing a low-boiling solvent.

32. (new) An adhesive for a printed wiring board employing the heat-resistant composition according to claim 6.

33. (new) An adhesive sheet for a printed wiring board employing the heat-resistant composition according to claim 6.

34. (new) A multilayer printed wiring board employing the heat-resistant composition according to claim 6.

35. (new) A sealant for a printed wiring board employing the heat-resistant composition according to claim 6.

36. (new) An insulating circuit protective film for a printed wiring board employing the heat-resistant composition according to claim 6.

37. (new) A circuit protective agent employing the heat-resistant composition according to claim 6.

38. (new) A cover-lay film employing the heat-resistant composition according to claim 6.

39. (new) A cover ink employing the heat-resistant composition according to claim 6.

40. (new) A substrate for a printed wiring board employing the heat-resistant composition according to claim 6.

41. (new) A metal-clad laminate employing the heat-resistant composition according to claim 6.

42. (new) A conductive paste for a printed wiring board employing the heat-resistant composition according to claim 6.